12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20240827002.1
Qualification of RFAB as an additional Fab site option and Assembly Site (CDAT) options for select devices
Change Notification / Sample Request

Date: August 28, 2024
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If samples or additional data are required, requests must be received within **30 days** of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the Change Management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

Sincerely,

Change Management Team
SC Business Services

20240827002.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TPS56C215RNNR	NULL
TPS56C215RNNT	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20240827002.1	PCN Date:	August 28, 2024
Title:	Qualification of RFAB as an additional Fab site option and Assembly Site (CDAT) options for select devices		
Customer Contact:	Change Management Team	Dept:	Quality Services
Proposed 1st Ship Date:	November 26, 2024	Sample requests accepted until:	September 27, 2024*

*Sample requests received after September 27, 2024 will not be supported.

Change Type:

☒	Assembly Site	☒	Design	☐	Wafer Bump Material
☐	Assembly Process	☒	Data Sheet	☐	Wafer Bump Process
☐	Assembly Materials	☐	Part number change	☒	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☒	Wafer Fab Material
☒	Packing/Shipping/Labeling	☐	Test Process	☒	Wafer Fab Process

PCN Details

Description of Change:

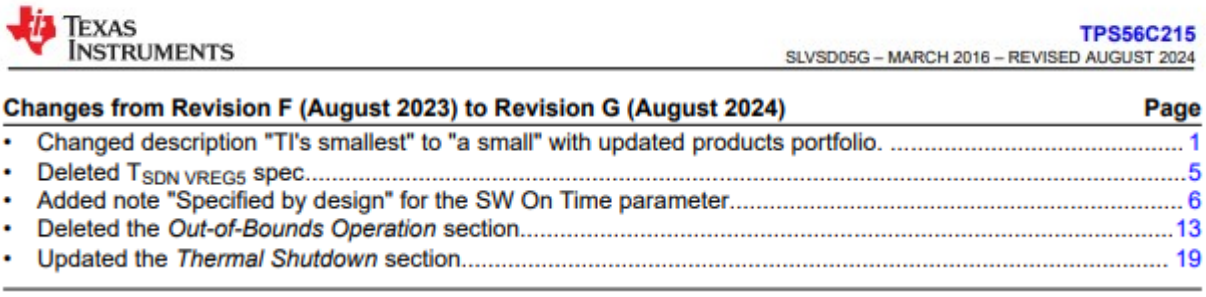
Texas Instruments is pleased to announce the qualification of its RFAB fabrication facility as an additional Wafer Fab option in addition to Assembly Site (CDAT) options for the devices listed below.

Current Fab Site			Additional Fab site		
Current Fab Site	**Process**	**Wafer Diameter**	**Additional Fab site**	**Process**	**Wafer Diameter**
MIHO8	LBC7.3	200mm	RFAB	LBC9PLV.2	300mm
RFAB	LBC7.3	300mm			

The die was also changed as a result of the process change to accommodate the change in Assembly technology.

No material differences between Assembly sites.

Assembly Site	Assembly Site Origin	Assembly Country Code	Assembly City
TI CLARK	QAB	PHL	Angeles City
UTAC	NSE	THA	Chnongchuan
TI CDAT	**CDA**	**CHN**	**Chengdu**



TEXAS INSTRUMENTS

TPS56C215

SLVSD05G – MARCH 2016 – REVISED AUGUST 2024

Changes from Revision F (August 2023) to Revision G (August 2024) **Page**

- Changed description "TI's smallest" to "a small" with updated products portfolio. 1
- Deleted $T_{SDN\ VREG5}$ spec. 5
- Added note "Specified by design" for the SW On Time parameter. 6
- Deleted the *Out-of-Bounds Operation* section. 13
- Updated the *Thermal Shutdown* section. 19

The datasheet number will be changing.

Device Family	Change From:	Change To:
TPS56C215	SLVSD05F	**SLVSD05G**

These changes may be reviewed at the datasheet links provided.
http://www.ti.com/product/TPS56C215

Reason for Change:

Supply Continuity

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive /

negative):

None

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
MIHO8	MH8	JPN	Ibaraki
RFAB	**RFB**	**USA**	**Richardson**

Die Rev:

Current	New
Die Rev [2P]	**Die Rev [2P]**
B0	**A1**

Assembly Site Information:

TI Clark	Assembly Site Origin (22L)	ASO: QAB
UTAC	Assembly Site Origin (22L)	ASO: NSE
TI CDAT	Assembly Site Origin (22L)	ASO: CDA

Sample product shipping label (not actual product label):

Product Affected:

TPS56C215RNNR	TPS56C215RNNT

Qualification Report

Approve Date 22-May-2024

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TPS56C215RNNR	QBS Reference: TPS51486RJER	QBS Reference: ROOMBADRLR	QBS Reference: TPS56C231RNNR	QBS Reference: TPS56C231RNNR	QBS Reference: TPS61288RQQR
HAST	A2	Biased HAST	110C/85%RH	264 Hours	-	3/231/0	-	-	-	-
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	2/154/0	-	2/154/0	3/231/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	3/231/0	-	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	3/231/0	-	2/154/0	3/231/0
TC	A4	Temperature Cycle	-55C/125C	700 Cycles	-	3/231/0	-	-	3/231/0	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	3/231/0	-	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	3/231/0	-	-	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	3/231/0	1/77/0	-	3/231/0	3/231/0
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0	-	1/77/0	3/231/0	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/2400/0	-	-	-	-
ESD	E2	ESD CDM	-	1500 Volts	-	-	-	1/3/0	1/3/0	-
ESD	E2	ESD HBM	-	3000 Volts	-	-	-	1/3/0	1/3/0	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	-	1/6/0	1/6/0	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	3/90/0	1/30/0	1/30/0	1/30/0	-
FTY	E6	Final Test Yield	-	-	-	-	-	1/1/0	3/3/0	-

QBS: Qual By Similarity
Qual Device TPS56C215RNNR is qualified at MSL2 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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